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(71) Applicants (*for all designated States except US*): **OLYMPUS CORPORATION [JP/JP]; 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). EVOTEC TECHNOLOGIES GMBH [DE/DE]; Merowingerplatz 1a, D-40225 Düsseldorf (DE).**

(72) Inventors; and

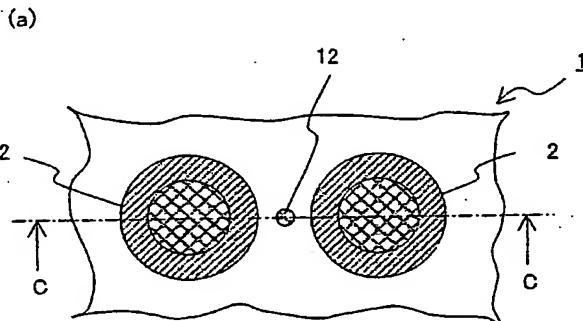
(75) Inventors/Applicants (*for US only*): **SEKINE, Katsumi [JP/JP]; c/o OLYMPUS CORPORATION, 43-2,**

Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). **TERAMOTO, Satoshi [JP/JP]; c/o OLYMPUS CORPORATION, 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). INAHASHI, Jun [JP/JP]; c/o OLYMPUS CORPORATION, 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). YAMAZAKI, Toshikatsu [JP/JP]; c/o OLYMPUS CORPORATION, 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). MICHINAKA, Akio [JP/JP]; c/o OLYMPUS CORPORATION, 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). MATSUO, Yutaka [JP/JP]; c/o OLYMPUS CORPORATION, 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP). KODAMA, Takuya [JP/JP]; c/o OLYMPUS CORPORATION, 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 1510072 (JP).**

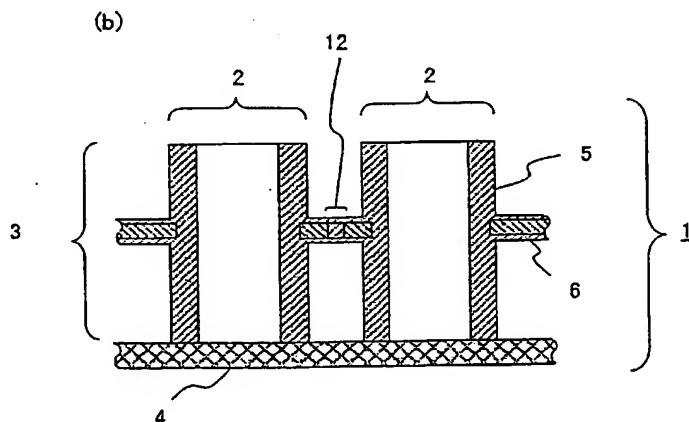
(74) Agent: **OSUGA, Yoshiyuki; 3rd Fl., Nibancho Bldg., 8-20, Nibancho, Chiyoda-ku, Tokyo 1020084 (JP).**

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(54) Title: MICROPLATE AND METHOD OF MANUFACTURING MICROPLATE



(57) Abstract: In a microplate (1) including wells (2) formed by covering openings of through-holes with a cover glass (4) having a light transmissible property on one side, the through-holes being formed on a resin plate (3) formed by covering an aluminum plate (6) with resin (5), which is plastic material, and extending through the resin plate (3) including the aluminum plate (6), an flow-through-hole (12) for allowing melt resin (5) for injection-molding of the resinplate (3) to pass is formed on the surface of the aluminum plate (6) within the range for forming the well (2) but at the positions where the wells (2) are not formed, so that resin (5) can easily flow to the opposite area of the aluminum plate (6).



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